Workshop on High Performance Computing for Materials Characterization, Design and Discovery

Description:

The event includes a two-and-a-half-day hands-on workshop along with participation in the XXV Latin American Symposium on Solid State Physics (SLAFES).

The event aims to enhance the capabilities of scientists in Latin America by complementing the efforts of local networks like SCALAC, Red-Clara, and LaRedCCA2 in utilizing high-performance computing (HPC) in materials science. This event addresses inequalities and promotes the adoption of HPC methodologies by covering topics such as modern parallel architectures, practical skills for non-IT experts in using open-source scientific codes, running hybrid programs with accelerators, and hands-on experience in configuring and managing calculations for materials research and visualization. The workshop offers an intensive program that balances theoretical knowledge with practical application, ensuring that participants gain a solid understanding of how to apply HPC techniques to their research endeavours in materials science.

Only a limited number of participants will be selected to attend the entire program at no registration fee. Additionally, a limited number of grants are available to support attendance for the entire program, with priority given to participants from Latin America.

21 - 26 October 2024

Barranquilla, Colombia

Deadline:
11 August 2024

DIRECTORS:

Carlos J. Barrios HERNANDEZ, UIS, Colombia
Javier A. MONTOYA, Universidad de Cartagena, ACCEFYN, Colombia
Camilo ESPEJO, Universidad del Norte, Colombia
Carlos C. PINILLA, Universidad del Norte, Colombia
Sandro SCANDOLO, ICTP, Italy

ICTP SCIENTIFIC CONTACT:

Ivan GIROTTO, ICTP, Italy

FURTHER INFORMATION:

E-mail: smr3966@ictp.it

Web: https://indico.ictp.it/event/10504/

Female scientists are encouraged to apply.

GRANTS:

A limited number of grants are available to support the attendance of selected participants, with priority given to participants from developing countries.
There is no registration fee.